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Intel - 5SGXMA7H2F35C2N Datasheet



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Understanding <u>Embedded - FPGAs (Field</u> <u>Programmable Gate Array)</u>

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Details	
Product Status	Obsolete
Number of LABs/CLBs	234720
Number of Logic Elements/Cells	622000
Total RAM Bits	51200000
Number of I/O	552
Number of Gates	-
Voltage - Supply	0.87V ~ 0.93V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	1152-BBGA, FCBGA
Supplier Device Package	1152-FBGA (35x35)
Purchase URL	https://www.e-xfl.com/product-detail/intel/5sgxma7h2f35c2n

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

Symbol	Description	Minimum	Maximum	Unit
V _{CCD_FPLL}	PLL digital power supply	-0.5	1.8	V
V _{CCA_FPLL}	PLL analog power supply	-0.5	3.4	V
VI	DC input voltage	-0.5	3.8	V
TJ	Operating junction temperature	-55	125	°C
T _{STG}	Storage temperature (No bias)	-65	150	°C
I _{OUT}	DC output current per pin	-25	40	mA

Table 3. Absolute Maximum Ratings for Stratix V Devices (Part 2 of 2)

Table 4 lists the absolute conditions for the transceiver power supply for Stratix V GX, GS, and GT devices.

Table 4. Transceiver Power Supply Absolute Conditions for Stratix V GX, GS, and GT Devices

Symbol	Description	Devices	Minimum	Maximum	Unit
V _{CCA_GXBL}	Transceiver channel PLL power supply (left side)	GX, GS, GT	-0.5	3.75	V
V _{CCA_GXBR}	Transceiver channel PLL power supply (right side)	GX, GS	-0.5	3.75	V
V _{CCA_GTBR}	Transceiver channel PLL power supply (right side)	GT	-0.5	3.75	V
V _{CCHIP_L}	Transceiver hard IP power supply (left side)	GX, GS, GT	-0.5	1.35	V
V _{CCHIP_R}	Transceiver hard IP power supply (right side)	GX, GS, GT	-0.5	1.35	V
V _{CCHSSI_L}	Transceiver PCS power supply (left side)	GX, GS, GT	-0.5	1.35	V
V _{CCHSSI_R}	Transceiver PCS power supply (right side)	GX, GS, GT	-0.5	1.35	V
V _{CCR_GXBL}	Receiver analog power supply (left side)	GX, GS, GT	-0.5	1.35	V
V _{CCR_GXBR}	Receiver analog power supply (right side)	GX, GS, GT	-0.5	1.35	V
V _{CCR_GTBR}	Receiver analog power supply for GT channels (right side)	GT	-0.5	1.35	V
V _{CCT_GXBL}	Transmitter analog power supply (left side)	GX, GS, GT	-0.5	1.35	V
V _{CCT_GXBR}	Transmitter analog power supply (right side)	GX, GS, GT	-0.5	1.35	V
V _{CCT_GTBR}	Transmitter analog power supply for GT channels (right side)	GT	-0.5	1.35	V
V _{CCL_GTBR}	Transmitter clock network power supply (right side)	GT	-0.5	1.35	V
V _{CCH_GXBL}	Transmitter output buffer power supply (left side)	GX, GS, GT	-0.5	1.8	V
V _{CCH_GXBR}	Transmitter output buffer power supply (right side)	GX, GS, GT	-0.5	1.8	V

Maximum Allowed Overshoot and Undershoot Voltage

During transitions, input signals may overshoot to the voltage shown in Table 5 and undershoot to -2.0 V for input currents less than 100 mA and periods shorter than 20 ns.

I/O Pin Leakage Current

Table 9 lists the Stratix V I/O pin leakage current specifications.

Table 9. I/	0 Pin Leakage	Current for Stratix 	/ Devices ⁽¹⁾
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Symbol	Description	Conditions	Min	Тур	Max	Unit
I _I	Input pin	$V_I = 0 V \text{ to } V_{CCIOMAX}$	-30	—	30	μA
I _{0Z}	Tri-stated I/O pin	$V_0 = 0 V$ to $V_{CCIOMAX}$	-30		30	μA

Note to Table 9:

(1) If $V_0 = V_{CCIO}$ to $V_{CCIOMax}$, 100 μ A of leakage current per I/O is expected.

Bus Hold Specifications

Table 10 lists the Stratix V device family bus hold specifications.

Table 10. Bus Hold Parameters for Stratix V Devices

							Va	CI0	-		-		
Parameter	Symbol	Conditions	1.2 V		1.5 V		1.8 V		2.5 V		3.0 V		Unit
			Min	Max									
Low sustaining current	I _{SUSL}	V _{IN} > V _{IL} (maximum)	22.5	_	25.0	_	30.0	_	50.0	_	70.0	_	μA
High sustaining current	I _{SUSH}	V _{IN} < V _{IH} (minimum)	-22.5	_	-25.0	_	-30.0	_	-50.0	_	-70.0	_	μA
Low overdrive current	I _{odl}	$0V < V_{IN} < V_{CCIO}$	_	120	_	160	_	200	_	300	_	500	μA
High overdrive current	I _{odh}	$0V < V_{IN} < V_{CCIO}$		-120		-160	_	-200		-300	_	-500	μA
Bus-hold trip point	V _{trip}	_	0.45	0.95	0.50	1.00	0.68	1.07	0.70	1.70	0.80	2.00	V

On-Chip Termination (OCT) Specifications

If you enable OCT calibration, calibration is automatically performed at power-up for I/Os connected to the calibration block. Table 11 lists the Stratix V OCT termination calibration accuracy specifications.

Table 11. OCT Calibration Accuracy Specifications for Stratix V Devices ⁽¹⁾ (Part 1 of 2)

				Calibratio	n Accuracy		
Symbol	Description	Conditions	C1	C2,I2	C3,I3, I3YY	C4,14	Unit
25-Ω R _S	Internal series termination with calibration (25- Ω setting)	V _{CCI0} = 3.0, 2.5, 1.8, 1.5, 1.2 V	±15	±15	±15	±15	%

I/O Standard	V _{IL(DI}	_{c)} (V)	V _{IH(D}	_{C)} (V)	V _{IL(AC)} (V)	V _{IH(AC)} (V)	V _{ol} (V)	V _{oh} (V)	I (mA)	I _{oh}
i/U Stanuaru	Min	Max	Min	Max	Max	Min	Max	Min	l _{oi} (mA)	(mA)
HSTL-18 Class I	_	V _{REF} – 0.1	V _{REF} + 0.1	_	$V_{REF} - 0.2$	V _{REF} + 0.2	0.4	V _{CCIO} – 0.4	8	-8
HSTL-18 Class II	_	V _{REF} – 0.1	V _{REF} + 0.1	_	V _{REF} - 0.2	V _{REF} + 0.2	0.4	V _{CCIO} – 0.4	16	-16
HSTL-15 Class I	_	V _{REF} – 0.1	V _{REF} + 0.1	_	V _{REF} - 0.2	V _{REF} + 0.2	0.4	V _{CCIO} – 0.4	8	-8
HSTL-15 Class II	_	V _{REF} – 0.1	V _{REF} + 0.1	_	V _{REF} - 0.2	V _{REF} + 0.2	0.4	V _{CCIO} – 0.4	16	-16
HSTL-12 Class I	-0.15	V _{REF} – 0.08	V _{REF} + 0.08	V _{CCIO} + 0.15	V _{REF} – 0.15	V _{REF} + 0.15	0.25* V _{CCI0}	0.75* V _{CCI0}	8	-8
HSTL-12 Class II	-0.15	V _{REF} – 0.08	V _{REF} + 0.08	V _{CCIO} + 0.15	V _{REF} – 0.15	V _{REF} + 0.15	0.25* V _{CCIO}	0.75* V _{CCI0}	16	-16
HSUL-12	_	V _{REF} – 0.13	V _{REF} + 0.13	_	V _{REF} – 0.22	V _{REF} + 0.22	0.1* V _{CCIO}	0.9* V _{CCI0}	_	_

Table 19. Single-Ended SSTL, HSTL, and HSUL I/O Standards Signal Specifications for Stratix V Devices (Part 2 of 2)

Table 20. Differential SSTL I/O Standards for Stratix V Devices

I/O Standard		V _{ccio} (V)		V _{SWIN}	_{G(DC)} (V)		V _{X(AC)} (V)		V _{swing(} ,	_{AC)} (V)
ijo Stanuaru	Min	Тур	Max	Min	Max	Min	Тур	Max	Min	Max
SSTL-2 Class I, II	2.375	2.5	2.625	0.3	V _{CCI0} + 0.6	V _{CCI0} /2- 0.2	_	V _{CCI0} /2 + 0.2	0.62	V _{CCI0} + 0.6
SSTL-18 Class I, II	1.71	1.8	1.89	0.25	V _{CCI0} + 0.6	V _{CCI0} /2- 0.175	_	V _{CCI0} /2 + 0.175	0.5	V _{CCI0} + 0.6
SSTL-15 Class I, II	1.425	1.5	1.575	0.2	(1)	V _{CCI0} /2- 0.15	_	V _{CCI0} /2 + 0.15	0.35	_
SSTL-135 Class I, II	1.283	1.35	1.45	0.2	(1)	V _{CCI0} /2- 0.15	V _{CCI0} /2	V _{CCI0} /2 + 0.15	2(V _{IH(AC)} - V _{REF})	2(V _{IL(AC)} - V _{REF})
SSTL-125 Class I, II	1.19	1.25	1.31	0.18	(1)	V _{CCI0} /2- 0.15	V _{CCI0} /2	V _{CCI0} /2 + 0.15	2(V _{IH(AC)} - V _{REF})	_
SSTL-12 Class I, II	1.14	1.2	1.26	0.18	_	V _{REF} -0.15	V _{CCI0} /2	V _{REF} + 0.15	-0.30	0.30

Note to Table 20:

(1) The maximum value for $V_{SWING(DC)}$ is not defined. However, each single-ended signal needs to be within the respective single-ended limits $(V_{IH(DC)} \text{ and } V_{IL(DC)})$.

I/O	I/O V _{ccio} (V)			V _{DIF(I}	_{DC)} (V)	V _{X(AC)} (V)				V _{CM(DC)} (V	V _{DIF(AC)} (V)		
Standard	Min	Тур	Max	Min	Max	Min	Тур	Max	Min	Тур	Max	Min	Max
HSTL-18 Class I, II	1.71	1.8	1.89	0.2	_	0.78	_	1.12	0.78	_	1.12	0.4	_
HSTL-15 Class I, II	1.425	1.5	1.575	0.2	_	0.68	_	0.9	0.68	_	0.9	0.4	_

Symbol/ Description	Conditions	Tra	nsceive Grade	r Speed 1	Tra	nsceive Grade	r Speed 2	Trai	nsceive Grade	r Speed 3	Unit
Description		Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	
	85– Ω setting		85 ± 30%		-	85 ± 30%			85 ± 30%		Ω
Differential on-	100–Ω setting	_	100 ± 30%		_	100 ± 30%		_	100 ± 30%		Ω
chip termination resistors ⁽²¹⁾	120–Ω setting	_	120 ± 30%		_	120 ± 30%		_	120 ± 30%		Ω
	150-Ω setting	_	150 ± 30%	_	_	150 ± 30%		_	150 ± 30%		Ω
	V _{CCR_GXB} = 0.85 V or 0.9 V full bandwidth		600		_	600	_		600		mV
V _{ICM} (AC and DC coupled)	V _{CCR_GXB} = 0.85 V or 0.9 V half bandwidth	_	600	_	_	600	_	_	600	_	mV
coupleu)	V _{CCR_GXB} = 1.0 V/1.05 V full bandwidth	_	700		_	700			700		mV
	V _{CCR_GXB} = 1.0 V half bandwidth		750	_	_	750	_	_	750	_	mV
t _{LTR} ⁽¹¹⁾	_	_	—	10	—	—	10	—	—	10	μs
t _{LTD} (12)	_	4			4			4			μs
t _{LTD_manual} ⁽¹³⁾		4			4			4	_		μs
t _{LTR_LTD_manual} ⁽¹⁴⁾		15			15	—		15	—		μs
Run Length	_	_		200		—	200		—	200	UI
Programmable equalization (AC Gain) ⁽¹⁰⁾	Full bandwidth (6.25 GHz) Half bandwidth (3.125 GHz)			16	_		16	_		16	dB

 Table 23. Transceiver Specifications for Stratix V GX and GS Devices ⁽¹⁾ (Part 4 of 7)

Table 23. Transceiver Specifications for Stratix V GX and GS Devices ⁽¹⁾ (Part 6 of 7)

Symbol/	Conditions	Trai	isceive Grade	r Speed 1	Trar	isceive Grade	r Speed 2	Tran	isceive Grade	er Speed e 3	Unit
Description		Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	
Inter-transceiver block transmitter channel-to- channel skew	xN PMA bonded mode			500	_		500	_		500	ps
CMU PLL											
Supported Data Range	_	600		12500	600	_	12500	600	_	8500/ 10312.5 (24)	Mbps
t _{pll_powerdown} ⁽¹⁵⁾	_	1		—	1	—	—	1	—	—	μs
t _{pll_lock} (16)	_		_	10	—	_	10	—	—	10	μs
ATX PLL	1										
	VCO post-divider L=2	8000		14100	8000	_	12500	8000	_	8500/ 10312.5 (24)	Mbps
Current and Date	L=4	4000	_	7050	4000	_	6600	4000	—	6600	Mbps
Supported Data Rate Range	L=8	2000	_	3525	2000	_	3300	2000	_	3300	Mbps
Kate Kange	L=8, Local/Central Clock Divider =2	1000	_	1762.5	1000		1762.5	1000		1762.5	Mbps
t _{pll_powerdown} (15)	_	1		_	1			1	—	_	μs
t _{pll_lock} ⁽¹⁶⁾	—			10	—	—	10	—	—	10	μs
fPLL	•			•					•		
Supported Data Range	_	600	_	3250/ 3125 ⁽²⁵⁾	600	_	3250/ 3125 ⁽²⁵⁾	600	_	3250/ 3125 ⁽²⁵⁾	Mbps
t _{pll_powerdown} ⁽¹⁵⁾	_	1	_	_	1	_	—	1	—	—	μs

Table 24 shows the maximum transmitter data rate for the clock network.

Table 24. Clock Network Maximum Data Rate Transmitter Specifications (1)

		ATX PLL			CMU PLL ⁽²⁾)		fPLL	
Clock Network	Non- bonded Mode (Gbps)	Bonded Mode (Gbps)	Channel Span	Non- bonded Mode (Gbps)	Bonded Mode (Gbps)	Channel Span	Non- bonded Mode (Gbps)	Bonded Mode (Gbps)	Channel Span
x1 ⁽³⁾	14.1	—	6	12.5	_	6	3.125	_	3
x6 ⁽³⁾	_	14.1	6	_	12.5	6	_	3.125	6
x6 PLL Feedback ⁽⁴⁾	_	14.1	Side- wide	_	12.5	Side- wide		_	_
xN (PCIe)	_	8.0	8	_	5.0	8	_	_	_
xN (Native PHY IP)	8.0	8.0	Up to 13 channels above and below PLL	7.99	7 00	Up to 13 channels above	3 1 2 5	3.125	Up to 13 channels above
	_	8.01 to 9.8304	Up to 7 channels above and below PLL	7.55	7.99	and below PLL	3.125	0.120	and below PLL

Notes to Table 24:

(1) Valid data rates below the maximum specified in this table depend on the reference clock frequency and the PLL counter settings. Check the MegaWizard message during the PHY IP instantiation.

(2) ATX PLL is recommended at 8 Gbps and above data rates for improved jitter performance.

(3) Channel span is within a transceiver bank.

(4) Side-wide channel bonding is allowed up to the maximum supported by the PHY IP.

Table 29 shows the V_{OD} settings for the GT channel.

Table 29.	Typical Von Setting	g for GT Channel, 1	EX Termination = 100 Ω
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Symbol	V _{OD} Setting	V _{op} Value (mV)
	0	0
	1	200
\mathbf{V}_{0D} differential peak to peak typical (1)	2	400
VOD unicicilitat peak to peak typical (*)	3	600
	4	800
	5	1000

Note:

(1) Refer to Figure 4.

Figure 6 shows the Stratix V DC gain curves for GT channels.

Figure 6. DC Gain Curves for GT Channels

Transceiver Characterization

This section summarizes the Stratix V transceiver characterization results for compliance with the following protocols:

- Interlaken
- 40G (XLAUI)/100G (CAUI)
- 10GBase-KR
- QSGMII
- XAUI
- SFI
- Gigabit Ethernet (Gbe / GIGE)
- SPAUI
- Serial Rapid IO (SRIO)
- CPRI
- OBSAI
- Hyper Transport (HT)
- SATA
- SAS
- CEI

Table 31. PLL Specifications for Stratix V Devices (Part 3 of 3)

Symbol	Parameter	Min	Тур	Max	Unit
f _{RES}	Resolution of VCO frequency ($f_{INPFD} = 100 \text{ MHz}$)	390625	5.96	0.023	Hz

Notes to Table 31:

(1) This specification is limited in the Quartus II software by the I/O maximum frequency. The maximum I/O frequency is different for each I/O standard.

(2) This specification is limited by the lower of the two: I/O f_{MAX} or f_{OUT} of the PLL.

- (3) A high input jitter directly affects the PLL output jitter. To have low PLL output clock jitter, you must provide a clean clock source < 120 ps.
- (4) f_{REF} is fIN/N when N = 1.
- (5) Peak-to-peak jitter with a probability level of 10⁻¹² (14 sigma, 99.9999999974404% confidence level). The output jitter specification applies to the intrinsic jitter of the PLL, when an input jitter of 30 ps is applied. The external memory interface clock output jitter specifications use a different measurement method and are available in Table 44 on page 52.
- (6) The cascaded PLL specification is only applicable with the following condition: a. Upstream PLL: 0.59Mhz ≤ Upstream PLL BW < 1 MHz b. Downstream PLL: Downstream PLL BW > 2 MHz
- (7) High bandwidth PLL settings are not supported in external feedback mode.
- (8) The external memory interface clock output jitter specifications use a different measurement method, which is available in Table 42 on page 50.
- (9) The VCO frequency reported by the Quartus II software in the PLL Usage Summary section of the compilation report takes into consideration the VCO post-scale counter K value. Therefore, if the counter K has a value of 2, the frequency reported can be lower than the f_{VCO} specification.
- (10) This specification only covers fractional PLL for low bandwidth. The f_{VCO} for fractional value range 0.05 0.95 must be \geq 1000 MHz, while f_{VCO} for fractional value range 0.20 0.80 must be \geq 1200 MHz.
- (11) This specification only covered fractional PLL for low bandwidth. The f_{VC0} for fractional value range 0.05-0.95 must be \geq 1000 MHz.
- (12) This specification only covered fractional PLL for low bandwidth. The f_{VC0} for fractional value range 0.20-0.80 must be \geq 1200 MHz.

DSP Block Specifications

Table 32 lists the Stratix V DSP block performance specifications.

			I	Peforman	ce			
Mode	C1	C2, C2L	12, 12L	C3	13, 13L, 13YY	C4	14	Unit
		Modes ι	ising one	DSP				4
Three 9 x 9	600	600	600	480	480	420	420	MHz
One 18 x 18	600	600	600	480	480	420	400	MHz
Two partial 18 x 18 (or 16 x 16)	600	600	600	480	480	420	400	MHz
One 27 x 27	500	500	500	400	400	350	350	MHz
One 36 x 18	500	500	500	400	400	350	350	MHz
One sum of two 18 x 18(One sum of 2 16 x 16)	500	500	500	400	400	350	350	MHz
One sum of square	500	500	500	400	400	350	350	MHz
One 18 x 18 plus 36 (a x b) + c	500	500	500	400	400	350	350	MHz
		Modes u	sing two l	DSPs	1		•	1
Three 18 x 18	500	500	500	400	400	350	350	MHz
One sum of four 18 x 18	475	475	475	380	380	300	300	MHz
One sum of two 27 x 27	465	465	450	380	380	300	290	MHz
One sum of two 36 x 18	475	475	475	380	380	300	300	MHz
One complex 18 x 18	500	500	500	400	400	350	350	MHz
One 36 x 36	475	475	475	380	380	300	300	MHz

Table 32. Block Performance Specifications for Stratix V DSP Devices (Part 1 of 2)

Mode	C1	C2, C2L	12, 12L	C3	13, 13L, 13YY	C4	14	Unit	
		Modes us	ing Three	DSPs					
One complex 18 x 25	425	425	415	340	340	275	265	MHz	
Modes using Four DSPs									
One complex 27 x 27	465	465	465	380	380	300	290	MHz	

Table 32. Block Performance Specifications for Stratix V DSP Devices (Part 2 of 2)

Memory Block Specifications

Table 33 lists the Stratix V memory block specifications.

Table 33. Memory Block Performance Specifications for Stratix V Devices ^{(1), (2)} (Part 1 of 2)

		Resour	ces Used	Performance							
Memory	Mode	ALUTS	Memory	C1	C2, C2L	C3	C4	12, 12L	13, 13L, 13YY	14	Unit
	Single port, all supported widths	0	1	450	450	400	315	450	400	315	MHz
MLAB	Simple dual-port, x32/x64 depth	0	1	450	450	400	315	450	400	315	MHz
IVILAD	Simple dual-port, x16 depth ⁽³⁾	0	1	675	675	533	400	675	533	400	MHz
	ROM, all supported widths	0	1	600	600	500	450	600	500	450	MHz

Gumbal	Conditions		C1		C2,	C2L, I	2, I2L	C3,	13, I3L	., I3YY		C4,I	4	II.a.iA
Symbol	Conditions	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
	SERDES factor J = 3 to 10	(6)	_	(8)	(6)	_	(8)	(6)	_	(8)	(6)		(8)	Mbps
f _{HSDR} (data rate)	SERDES factor J = 2, uses DDR Registers	(6)		(7)	(6)	_	(7)	(6)		(7)	(6)		(7)	Mbps
	SERDES factor J = 1, uses SDR Register	(6)	_	(7)	(6)	_	(7)	(6)	_	(7)	(6)		(7)	Mbps
DPA Mode														
DPA run length	_			1000 0			1000 0		_	1000 0		_	1000 0	UI
Soft CDR mode	•													
Soft-CDR PPM tolerance	_	_	_	300	_	_	300	_	_	300	_		300	± PPM
Non DPA Mode	Non DPA Mode													
Sampling Window	—			300			300			300			300	ps

Table 36. High-Speed I/O Specifications for Stratix V Devices ^{(1), (2)} (Part 4 of 4)

Notes to Table 36:

(1) When J = 3 to 10, use the serializer/deserializer (SERDES) block.

(2) When J = 1 or 2, bypass the SERDES block.

(3) This only applies to DPA and soft-CDR modes.

(4) Clock Boost Factor (W) is the ratio between the input data rate to the input clock rate.

(5) This is achieved by using the **LVDS** clock network.

(6) The minimum specification depends on the clock source (for example, the PLL and clock pin) and the clock routing resource (global, regional, or local) that you use. The I/O differential buffer and input register do not have a minimum toggle rate.

(7) The maximum ideal frequency is the SERDES factor (J) x the PLL maximum output frequency (fOUT) provided you can close the design timing and the signal integrity simulation is clean.

(8) You can estimate the achievable maximum data rate for non-DPA mode by performing link timing closure analysis. You must consider the board skew margin, transmitter delay margin, and receiver sampling margin to determine the maximum data rate supported.

(9) If the receiver with DPA enabled and transmitter are using shared PLLs, the minimum data rate is 150 Mbps.

(10) You must calculate the leftover timing margin in the receiver by performing link timing closure analysis. You must consider the board skew margin, transmitter channel-to-channel skew, and receiver sampling margin to determine leftover timing margin.

(11) The F_{MAX} specification is based on the fast clock used for serial data. The interface F_{MAX} is also dependent on the parallel clock domain which is design-dependent and requires timing analysis.

(12) Stratix V RX LVDS will need DPA. For Stratix V TX LVDS, the receiver side component must have DPA.

(13) Stratix V LVDS serialization and de-serialization factor needs to be x4 and above.

(14) Requires package skew compensation with PCB trace length.

(15) Do not mix single-ended I/O buffer within LVDS I/O bank.

(16) Chip-to-chip communication only with a maximum load of 5 pF.

(17) When using True LVDS RX channels for emulated LVDS TX channel, only serialization factors 1 and 2 are supported.

Speed Grade	Min	Max	Unit
C4,I4	8	16	ps

Table 40. DQS Phase Offset Delay Per Setting for Stratix V Devices ^{(1), (2)} (Part 2 of 2)

Notes to Table 40:

(1) The typical value equals the average of the minimum and maximum values.

(2) The delay settings are linear with a cumulative delay variation of 40 ps for all speed grades. For example, when using a -2 speed grade and applying a 10-phase offset setting to a 90° phase shift at 400 MHz, the expected average cumulative delay is [625 ps + (10 × 10 ps) ± 20 ps] = 725 ps ± 20 ps.

Table 41 lists the DQS phase shift error for Stratix V devices.

Table 41. DQS Phase Shift Error Specification for DLL-Delayed Clock (t_{DQS_PSERR}) for Stratix V Devices ⁽¹⁾

Number of DQS Delay Buffers	C1	C2, C2L, I2, I2L	C3, I3, I3L, I3YY	C4,14	Unit
1	28	28	30	32	ps
2	56	56	60	64	ps
3	84	84	90	96	ps
4	112	112	120	128	ps

Notes to Table 41:

(1) This error specification is the absolute maximum and minimum error. For example, skew on three DQS delay buffers in a -2 speed grade is ± 78 ps or ± 39 ps.

Table 42 lists the memory output clock jitter specifications for Stratix V devices.

Clock Network	Parameter	Parameter Symbol		C1		C2, C2L, I2, I2L		C3, I3, I3L, I3YY		C4,14	
NELWUIK		-	Min	Max	Min	Max	Min	Max	Min	Max	
	Clock period jitter	t _{JIT(per)}	-50	50	-50	50	-55	55	-55	55	ps
Regional	Cycle-to-cycle period jitter	$t_{\rm JIT(cc)}$	-100	100	-100	100	-110	110	-110	110	ps
	Duty cycle jitter	$t_{JIT(duty)}$	-50	50	-50	50	-82.5	82.5	-82.5	82.5	ps
	Clock period jitter	t _{JIT(per)}	-75	75	-75	75	-82.5	82.5	-82.5	82.5	ps
Global	Cycle-to-cycle period jitter	$t_{\text{JIT(cc)}}$	-150	150	-150	150	-165	165	-165	165	ps
	Duty cycle jitter	$t_{JIT(duty)}$	-75	75	-75	75	-90	90	-90	90	ps

Clock	Clock letwork Parameter Symbo		C1		C2, C2L, I2, I2L		C3, I3, I3L, I3YY		C4,14		Unit
NELWURK			Min	Max	Min	Max	Min	Max	Min	Max	
	Clock period jitter	$t_{JIT(per)}$	-25	25	-25	25	-30	30	-35	35	ps
PHY Clock	Cycle-to-cycle period jitter	$t_{\text{JIT(cc)}}$	-50	50	-50	50	-60	60	-70	70	ps
	Duty cycle jitter	$t_{\text{JIT}(\text{duty})}$	-37.5	37.5	-37.5	37.5	-45	45	-56	56	ps

Table 42. Memory Output Clock Jitter Specification for Stratix V Devices (1), (Part 2 of 2) (2), (3)

Notes to Table 42:

(1) The clock jitter specification applies to the memory output clock pins generated using differential signal-splitter and DDIO circuits clocked by a PLL output routed on a PHY, regional, or global clock network as specified. Altera recommends using PHY clock networks whenever possible.

(2) The clock jitter specification applies to the memory output clock pins clocked by an integer PLL.

(3) The memory output clock jitter is applicable when an input jitter of 30 ps peak-to-peak is applied with bit error rate (BER) -12, equivalent to 14 sigma.

OCT Calibration Block Specifications

Table 43 lists the OCT calibration block specifications for Stratix V devices.

Table 43. OCT Calibration Block Specifications for Stratix V Devices

Symbol	Description	Min	Тур	Max	Unit
OCTUSRCLK	Clock required by the OCT calibration blocks		_	20	MHz
T _{OCTCAL}	Number of OCTUSRCLK clock cycles required for OCT $\rm R_S/R_T$ calibration	_	1000	_	Cycles
T _{OCTSHIFT}	Number of OCTUSRCLK clock cycles required for the OCT code to shift out	—	32	_	Cycles
T _{RS_RT}	Time required between the dyn_term_ctrl and oe signal transitions in a bidirectional I/O buffer to dynamically switch between OCT R_S and R_T (Figure 10)	_	2.5		ns

Figure 10 shows the timing diagram for the oe and dyn_term_ctrl signals.

Figure 10. Timing Diagram for oe and dyn_term_ctrl Signals

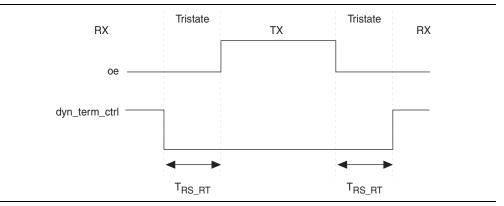


Table 50 lists the timing parameters for Stratix V devices for FPP configuration when the DCLK-to-DATA[] ratio is 1.

Table 50. FPP Timing Parameters for Stratix V Devices (1)

Symbol	Parameter	Minimum	Maximum	Units
t _{CF2CD}	nCONFIG low to CONF_DONE low	—	600	ns
t _{CF2ST0}	nCONFIG low to nSTATUS low	—	600	ns
t _{CFG}	nCONFIG low pulse width	2	—	μS
t _{status}	nSTATUS low pulse width	268	1,506 ⁽²⁾	μS
t _{CF2ST1}	nCONFIG high to nSTATUS high	—	1,506 ⁽³⁾	μS
t _{CF2CK} (6)	nCONFIG high to first rising edge on DCLK	1,506	_	μS
t _{ST2CK} ⁽⁶⁾	nSTATUS high to first rising edge of DCLK	2	_	μS
t _{DSU}	DATA [] setup time before rising edge on DCLK	5.5	_	ns
t _{DH}	DATA [] hold time after rising edge on DCLK	0	_	ns
t _{CH}	DCLK high time	$0.45\times1/f_{MAX}$	—	S
t _{CL}	DCLK low time	$0.45\times1/f_{MAX}$	—	S
t _{CLK}	DCLK period	1/f _{MAX}	_	S
f	DCLK frequency (FPP ×8/×16)	—	125	MHz
f _{MAX}	DCLK frequency (FPP ×32)	—	100	MHz
t _{CD2UM}	CONF_DONE high to user mode ⁽⁴⁾	175	437	μS
+	CONTRACT high to an union analysis	4 × maximum		
t _{CD2CU}	CONF_DONE high to CLKUSR enabled	DCLK period	—	
t _{CD2UMC}	CONF_DONE high to user mode with CLKUSR option on	$\begin{array}{c} t_{\text{CD2CU}} + \\ (8576 \times \text{CLKUSR} \\ \text{period}) \ ^{(5)} \end{array}$	_	_

Notes to Table 50:

(1) Use these timing parameters when the decompression and design security features are disabled.

(2) This value is applicable if you do not delay configuration by extending the nCONFIG or nSTATUS low pulse width.

(3) This value is applicable if you do not delay configuration by externally holding the nSTATUS low.

- (4) The minimum and maximum numbers apply only if you chose the internal oscillator as the clock source for initializing the device.
- (5) To enable the CLKUSR pin as the initialization clock source and to obtain the maximum frequency specification on these pins, refer to the Initialization section of the "Configuration, Design Security, and Remote System Upgrades in Stratix V Devices" chapter.
- (6) If nSTATUS is monitored, follow the t_{ST2CK} specification. If nSTATUS is not monitored, follow the t_{CF2CK} specification.

FPP Configuration Timing when DCLK-to-DATA [] > 1

Figure 13 shows the timing waveform for FPP configuration when using a MAX II device, MAX V device, or microprocessor as an external host. This waveform shows timing when the DCLK-to-DATA [] ratio is more than 1.

Active Serial Configuration Timing

Table 52 lists the DCLK frequency specification in the AS configuration scheme.

Table 52.	DCLK Frequency	Specification in the <i>l</i>	AS Configuration Scheme	(1), (2)
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Minimum	Typical	Maximum	Unit
5.3	7.9	12.5	MHz
10.6	15.7	25.0	MHz
21.3	31.4	50.0	MHz
42.6	62.9	100.0	MHz

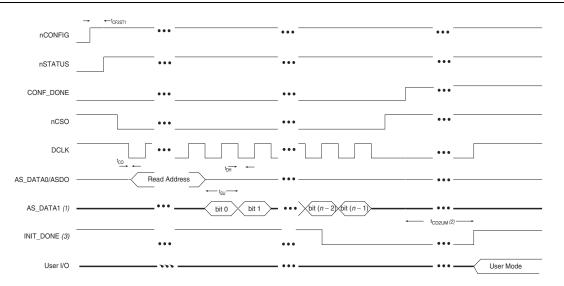
Notes to Table 52:

(1) This applies to the DCLK frequency specification when using the internal oscillator as the configuration clock source.

(2) The AS multi-device configuration scheme does not support DCLK frequency of 100 MHz.

Figure 14 shows the single-device configuration setup for an AS ×1 mode.





Notes to Figure 14:

- (1) If you are using AS $\times 4$ mode, this signal represents the AS_DATA[3..0] and EPCQ sends in 4-bits of data for each DCLK cycle.
- (2) The initialization clock can be from internal oscillator or CLKUSR pin.
- (3) After the option bit to enable the INIT_DONE pin is configured into the device, the INIT_DONE goes low.

Table 53 lists the timing parameters for AS $\times 1$ and AS $\times 4$ configurations in Stratix V devices.

Symbol	Parameter	Minimum	Maximum	Units
t _{CO}	DCLK falling edge to AS_DATA0/ASDO output	—	2	ns
t _{SU}	Data setup time before falling edge on DCLK	1.5	—	ns
t _H	Data hold time after falling edge on DCLK	0	—	ns

Symbol	Parameter	Minimum	Maximum	Units
t _{CD2UM}	CONF_DONE high to user mode (3)	175	437	μS
t _{CD2CU}	CONF_DONE high to CLKUSR enabled	4 × maximum DCLK period	_	—
t _{CD2UMC}	CONF_DONE high to user mode with CLKUSR option on	t _{cd2cu} + (8576 × clkusr period)	_	—

Table 53. AS Timing Parameters for AS \times 1 and AS \times 4 Configurations in Stratix V Devices ^{(1), (2)} (Part 2 of 2)

Notes to Table 53:

(1) The minimum and maximum numbers apply only if you choose the internal oscillator as the clock source for initializing the device.

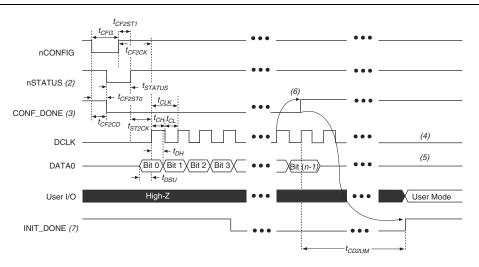
(2) t_{CF2CD}, t_{CF2ST0}, t_{CF2ST0}, t_{CF6}, t_{STATUS}, and t_{CF2ST1} timing parameters are identical to the timing parameters for PS mode listed in Table 54 on page 63.

(3) To enable the CLKUSR pin as the initialization clock source and to obtain the maximum frequency specification on this pin, refer to the Initialization section of the "Configuration, Design Security, and Remote System Upgrades in Stratix V Devices" chapter.

Passive Serial Configuration Timing

Figure 15 shows the timing waveform for a passive serial (PS) configuration when using a MAX II device, MAX V device, or microprocessor as an external host.

Figure 15. PS Configuration Timing Waveform ⁽¹⁾



Notes to Figure 15:

- (1) The beginning of this waveform shows the device in user mode. In user mode, nCONFIG, nSTATUS, and CONF_DONE are at logic high levels. When nCONFIG is pulled low, a reconfiguration cycle begins.
- (2) After power-up, the Stratix V device holds <code>nSTATUS</code> low for the time of the POR delay.
- (3) After power-up, before and during configuration, CONF DONE is low.
- (4) Do not leave DCLK floating after configuration. You can drive it high or low, whichever is more convenient.
- (5) DATAO is available as a user I/O pin after configuration. The state of this pin depends on the dual-purpose pin settings in the **Device and Pins Option**.
- (6) To ensure a successful configuration, send the entire configuration data to the Stratix V device. CONF_DONE is released high after the Stratix V device receives all the configuration data successfully. After CONF_DONE goes high, send two additional falling edges on DCLK to begin initialization and enter user mode.
- (7) After the option bit to enable the INIT DONE pin is configured into the device, the INIT DONE goes low.

Table 54 lists the PS configuration timing parameters for Stratix V devices.

Table 54. PS Timing Parameters for Stratix V Devices

Symbol	Parameter	Minimum	Maximum	Units
t _{CF2CD}	nCONFIG low to CONF_DONE low	—	600	ns
t _{CF2ST0}	nCONFIG low to nSTATUS low	—	600	ns
t _{CFG}	nCONFIG low pulse width	2	—	μS
t _{status}	nSTATUS low pulse width	268	1,506 ⁽¹⁾	μS
t _{CF2ST1}	nCONFIG high to nSTATUS high	—	1,506 ⁽²⁾	μS
t _{CF2CK} (5)	nCONFIG high to first rising edge on DCLK	1,506	—	μS
t _{ST2CK} ⁽⁵⁾	nSTATUS high to first rising edge of DCLK	2	—	μS
t _{DSU}	DATA[] setup time before rising edge on DCLK	5.5	—	ns
t _{DH}	DATA[] hold time after rising edge on DCLK	0	—	ns
t _{CH}	DCLK high time	$0.45\times 1/f_{MAX}$	—	S
t _{CL}	DCLK low time	$0.45\times 1/f_{MAX}$	—	S
t _{CLK}	DCLK period	1/f _{MAX}	—	S
f _{MAX}	DCLK frequency	—	125	MHz
t _{CD2UM}	CONF_DONE high to user mode (3)	175	437	μS
t _{CD2CU}	CONF_DONE high to CLKUSR enabled	4 × maximum DCLK period	_	_
t _{CD2UMC}	CONF_DONE high to user mode with CLKUSR option on	t_{CD2CU} + (8576 × CLKUSR period) ⁽⁴⁾	_	_

Notes to Table 54:

(1) This value is applicable if you do not delay configuration by extending the nCONFIG or nSTATUS low pulse width.

(2) This value is applicable if you do not delay configuration by externally holding the nSTATUS low.

(3) The minimum and maximum numbers apply only if you choose the internal oscillator as the clock source for initializing the device.

(4) To enable the CLKUSR pin as the initialization clock source and to obtain the maximum frequency specification on these pins, refer to the "Initialization" section.

(5) If nSTATUS is monitored, follow the t_{ST2CK} specification. If nSTATUS is not monitored, follow the t_{CF2CK} specification.

Initialization

Table 55 lists the initialization clock source option, the applicable configuration schemes, and the maximum frequency.

Table 55. Initialization Clock Source Option and the Maximu	m Frequency
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Initialization Clock Source	Configuration Schemes	Maximum Frequency	Minimum Number of Clock Cycles ⁽¹⁾
Internal Oscillator	AS, PS, FPP	12.5 MHz	
CLKUSR	AS, PS, FPP ⁽²⁾	125 MHz	8576
DCLK	PS, FPP	125 MHz	

Notes to Table 55:

(1) The minimum number of clock cycles required for device initialization.

(2) To enable CLKUSR as the initialization clock source, turn on the Enable user-supplied start-up clock (CLKUSR) option in the Quartus II software from the General panel of the Device and Pin Options dialog box.

Remote System Upgrades

Table 56 lists the timing parameter specifications for the remote system upgrade circuitry.

Table 56. Remote System Upgrade Circuitry Timing Specifications

Parameter	Minimum	Maximum	Unit		
t _{RU_nCONFIG} ⁽¹⁾	250	—	ns		
t _{RU_nRSTIMER} ⁽²⁾	250	—	ns		

Notes to Table 56:

- (1) This is equivalent to strobing the reconfiguration input of the ALTREMOTE_UPDATE megafunction high for the minimum timing specification. For more information, refer to the Remote System Upgrade State Machine section of the "Configuration, Design Security, and Remote System Upgrades in Stratix V Devices" chapter.
- (2) This is equivalent to strobing the reset_timer input of the ALTREMOTE_UPDATE megafunction high for the minimum timing specification. For more information, refer to the User Watchdog Timer section of the "Configuration, Design Security, and Remote System Upgrades in Stratix V Devices" chapter.

User Watchdog Internal Circuitry Timing Specification

Table 57 lists the operating range of the 12.5-MHz internal oscillator.

Table 57. 12.5-MHz Internal Oscillator Specifications

Minimum	Typical	Maximum	Units		
5.3	7.9	12.5	MHz		

I/O Timing

Altera offers two ways to determine I/O timing—the Excel-based I/O Timing and the Quartus II Timing Analyzer.

Excel-based I/O timing provides pin timing performance for each device density and speed grade. The data is typically used prior to designing the FPGA to get an estimate of the timing budget as part of the link timing analysis. The Quartus II Timing Analyzer provides a more accurate and precise I/O timing data based on the specifics of the design after you complete place-and-route.

 You can download the Excel-based I/O Timing spreadsheet from the Stratix V Devices Documentation web page.

Programmable IOE Delay

Table 58 lists the Stratix V IOE programmable delay settings.

Table 58. IOE Programmable Delay for Stratix V Devices (Part 1 of 2)

Deremeter	Available							Slow N	lodel			
Parameter (1)	Available Settings	Offset (2)	Industrial	Commercial	C1	C2	C3	C4	12	13, 13YY	14	Unit
D1	64	0	0.464	0.493	0.838	0.838	0.924	1.011	0.844	0.921	1.006	ns
D2	32	0	0.230	0.244	0.415	0.415	0.459	0.503	0.417	0.456	0.500	ns

Letter	Subject Definitions						
	V _{CM(DC)}	DC common mode input voltage.					
	V _{ICM}	Input common mode voltage—The common mode of the differential signal at the receiver.					
	V _{ID}	Input differential voltage swing—The difference in voltage between the positive and complementary conductors of a differential transmission at the receiver.					
	V _{DIF(AC)}	AC differential input voltage—Minimum AC input differential voltage required for switching.					
	V _{DIF(DC)}	DC differential input voltage— Minimum DC input differential voltage required for switching.					
	V _{IH}	Voltage input high—The minimum positive voltage applied to the input which is accepted by the device as a logic high.					
	V _{IH(AC)}	High-level AC input voltage					
	V _{IH(DC)}	High-level DC input voltage					
V	V _{IL}	Voltage input low—The maximum positive voltage applied to the input which is accepted by the device as a logic low.					
	V _{IL(AC)}	Low-level AC input voltage					
	V _{IL(DC)}	Low-level DC input voltage					
	V _{OCM}	Output common mode voltage—The common mode of the differential signal at the transmitter.					
	V _{OD}	Output differential voltage swing—The difference in voltage between the positive and complementary conductors of a differential transmission at the transmitter.					
	V _{SWING}	Differential input voltage					
	V _X	Input differential cross point voltage					
	V _{OX}	Output differential cross point voltage					
W	W	High-speed I/O block—clock boost factor					
X							
Y	_	_					
Z							

Table 60. Glossary (Part 4 of 4)